

$V_{DRM}$  = 1800 V  
 $I_{T(AV)M}$  = 4390 A  
 $I_{T(RMS)}$  = 6890 A  
 $I_{TSM}$  =  $64 \cdot 10^3$  A  
 $V_{TO}$  = 0.85 V  
 $r_T$  = 0.07 mΩ

# Phase Control Thyristor

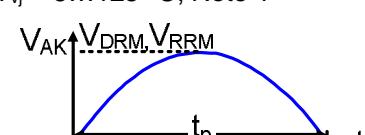
## 5STP 42L1800

Doc. No. 5SYA1075-03 Mar. 19

- Patented free-floating silicon technology
- Low on-state and switching losses
- Designed for traction, energy and industrial applications
- Optimum power handling capability
- Interdigitated amplifying gate

### Blocking

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	5STP 42L1800		Unit
Max repetitive peak forward and reverse blocking voltage	$V_{DRM}$ , $V_{RRM}$	$f = 50$ Hz, $t_p = 10$ ms, $T_{vj} = 5 \dots 125$ °C, Note 1 	1800		V
Critical rate of rise of commutating voltage	$dv/dt_{crit}$	Exp. to $0.67 \cdot V_{DRM}$ , $T_{vj} = 125$ °C	1000		V/μs

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Forward leakage current	$I_{DRM}$	$V_{DRM}$ , $T_{vj} = 125$ °C			300	mA
Reverse leakage current	$I_{RRM}$	$V_{RRM}$ , $T_{vj} = 125$ °C			300	mA

Note 1: Voltage de-rating factor of 0.11% per °C is applicable for  $T_{vj}$  below +5 °C.

### Mechanical data

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	$F_M$		63	70	84	kN
Acceleration	a	Device unclamped			50	m/s <sup>2</sup>
Acceleration	a	Device clamped			100	m/s <sup>2</sup>

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				1.45	kg
Housing thickness	H	$F_M = 70$ kN, $T_a = 25$ °C	25.8		26.4	mm
Surface creepage distance	D <sub>s</sub>		36			mm
Air strike distance	D <sub>a</sub>		15			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

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**On-state****Maximum rated values<sup>1)</sup>**

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	$I_{T(AV)M}$	Half sine wave, $T_c = 70^\circ C$			4390	A
RMS on-state current	$I_{T(RMS)}$				6890	A
Peak non-repetitive surge current	$I_{TSM}$	$t_p = 10 \text{ ms}, T_{vj} = 125^\circ C$ , sine half wave,			$64 \cdot 10^3$	A
Limiting load integral	$I^2t$	$V_D = V_R = 0 \text{ V}$ , after surge			$20.48 \cdot 10^6$	$\text{A}^2\text{s}$
Peak non-repetitive surge current	$I_{TSM}$	$t_p = 10 \text{ ms}, T_{vj} = 125^\circ C$ , sine half wave,			$40 \cdot 10^3$	A
Limiting load integral	$I^2t$	$V_R = 0.6 \cdot V_{RRM}$ , after surge			$8 \cdot 10^6$	$\text{A}^2\text{s}$

**Characteristic values**

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	$V_T$	$I_T = 3000 \text{ A}, T_{vj} = 125^\circ C$			1.05	V
Threshold voltage	$V_{(TO)}$				0.85	V
Slope resistance	$r_T$	$I_T = 2500 \text{ A} - 7500 \text{ A}, T_{vj} = 125^\circ C$			0.07	$\text{m}\Omega$
Holding current	$I_H$	$T_{vj} = 25^\circ C$			150	mA
		$T_{vj} = 125^\circ C$			100	mA
Latching current	$I_L$	$T_{vj} = 25^\circ C$			800	mA
		$T_{vj} = 125^\circ C$			500	mA

**Switching****Maximum rated values<sup>1)</sup>**

Parameter	Symbol	Conditions	min	typ	max	Unit
Critical rate of rise of on-state current	$di/dt_{crit}$	$T_{vj} = 125^\circ C$ , $I_{TRM} = 3000 \text{ A}$ , $V_D \leq 0.67 \cdot V_{DRM}$ , $I_{FG} = 2 \text{ A}, t_r = 0.5 \mu\text{s}$	Cont. $f = 50 \text{ Hz}$		250	$\text{A}/\mu\text{s}$
			Cont. $f = 1 \text{ Hz}$		1000	$\text{A}/\mu\text{s}$
Circuit-commutated turn-off time	$t_q$	$T_{vj} = 125^\circ C, I_{TRM} = 2000 \text{ A}$ , $V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu\text{s}$ , $V_D \leq 0.67 \cdot V_{DRM}, dv_D/dt = 20 \text{ V}/\mu\text{s}$			250	$\mu\text{s}$

**Characteristic values**

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	$Q_{rr}$	$T_{vj} = 125^\circ C, I_{TRM} = 2000 \text{ A}$ ,	800		1900	$\mu\text{As}$
Reverse recovery current	$I_{RM}$	$V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu\text{s}$			95	A
Gate turn-on delay time	$t_{gd}$	$T_{vj} = 25^\circ C, V_D = 0.4 \cdot V_{RM}$ , $I_{FG} = 2 \text{ A}, t_r = 0.5 \mu\text{s}$			3	$\mu\text{s}$

## Triggering

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward gate voltage	V <sub>FGM</sub>				12	V
Peak forward gate current	I <sub>FGM</sub>				10	A
Peak reverse gate voltage	V <sub>RGM</sub>				10	V
Average gate power loss	P <sub>G(AV)</sub>				see Fig. 7	W

*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Gate-trigger voltage	V <sub>GT</sub>	T <sub>vj</sub> = 25 °C			2.6	V
Gate-trigger current	I <sub>GT</sub>	T <sub>vj</sub> = 25 °C			400	mA
Gate non-trigger voltage	V <sub>GD</sub>	V <sub>D</sub> = 0.4 · V <sub>DRM</sub> , T <sub>vjmax</sub> = 125 °C			0.3	V
Gate non-trigger current	I <sub>GD</sub>	V <sub>D</sub> = 0.4 · V <sub>DRM</sub> , T <sub>vjmax</sub> = 125 °C			10	mA

## Thermal

*Maximum rated values<sup>1)</sup>*

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T <sub>vj</sub>				125	°C
Storage temperature range	T <sub>stg</sub>		-40		140	°C

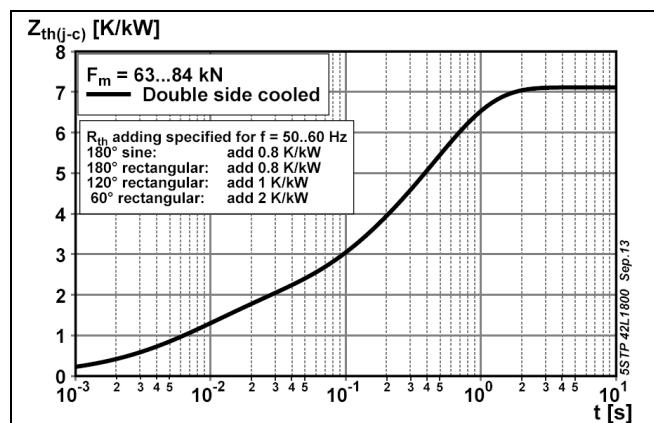
*Characteristic values*

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case,	R <sub>th(j-c)</sub>	Double-side cooled F <sub>m</sub> = 63... 84 kN			7	K/kW
	R <sub>th(j-c)A</sub>	Anode-side cooled F <sub>m</sub> = 63... 84 kN			14	K/kW
	R <sub>th(j-c)C</sub>	Cathode-side cooled F <sub>m</sub> = 63... 84 kN			14	K/kW
Thermal resistance case to heatsink,	R <sub>th(c-h)</sub>	Double-side cooled F <sub>m</sub> = 63... 84 kN			1.5	K/kW
	R <sub>th(c-h)</sub>	Single-side cooled F <sub>m</sub> = 63... 84 kN			3	K/kW

**Analytical function for transient thermal impedance:**

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
R <sub>i</sub> (K/kW)	4.700	0.853	1.070	0.490
τ <sub>i</sub> (s)	0.4787	0.0824	0.0104	0.0041



**Fig. 1** Transient thermal impedance (junction-to-case) vs. time

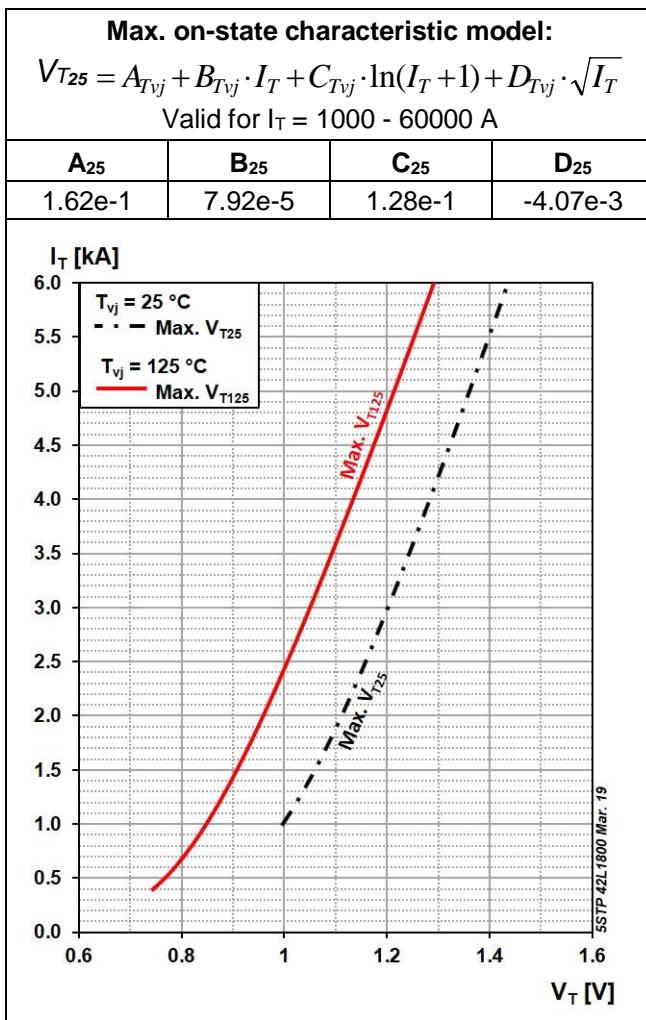


Fig. 2 On-state voltage characteristics

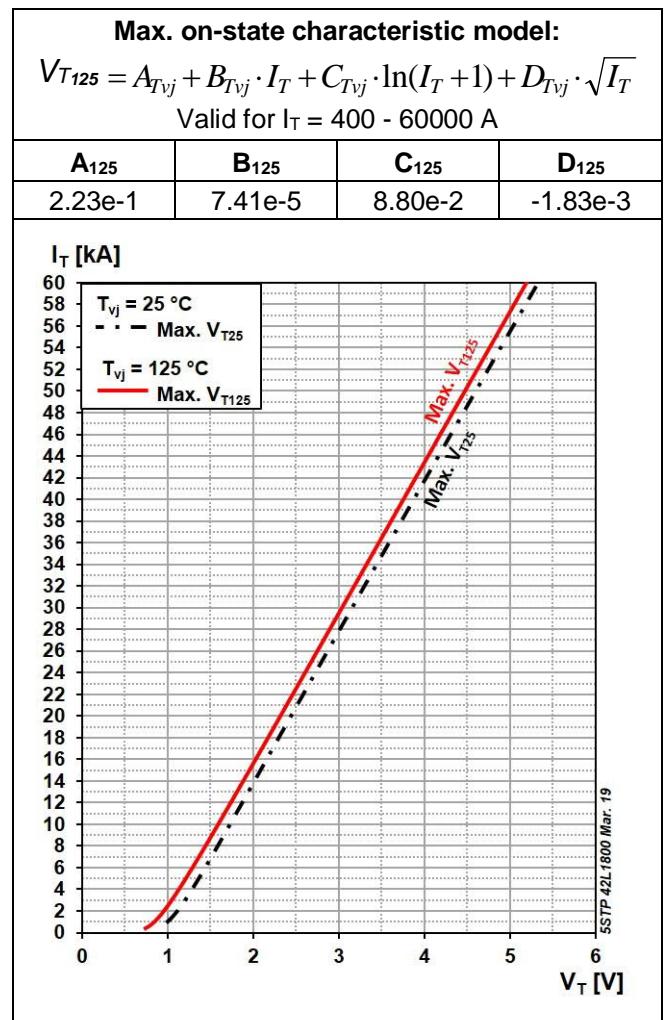


Fig. 3 On-state voltage characteristics

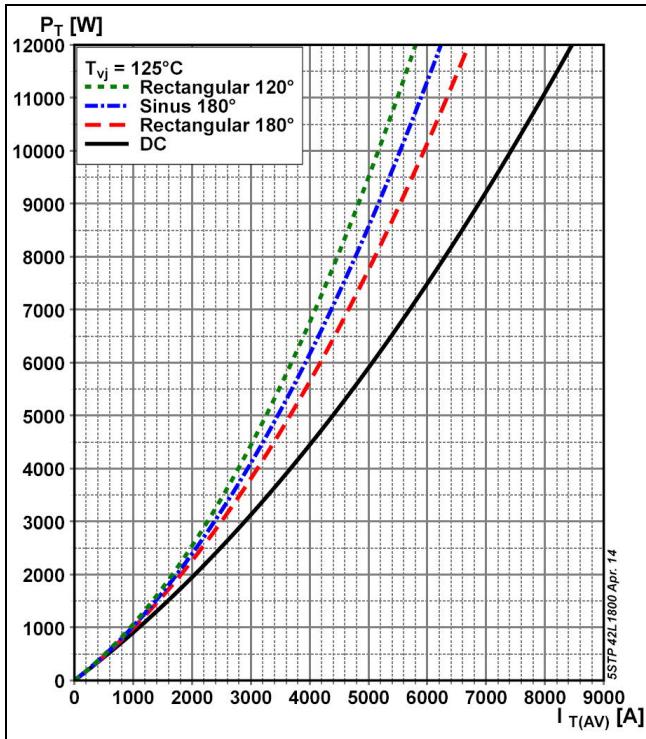


Fig. 4 On-state power dissipation vs. mean on-state current, turn-on losses excluded

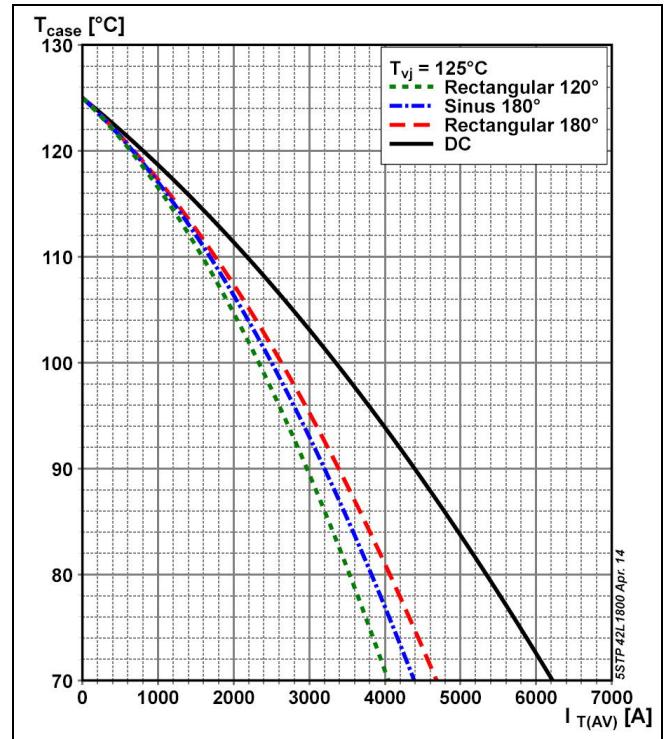


Fig. 5 Max. permissible case temperature vs. mean on-state current, switching losses ignored

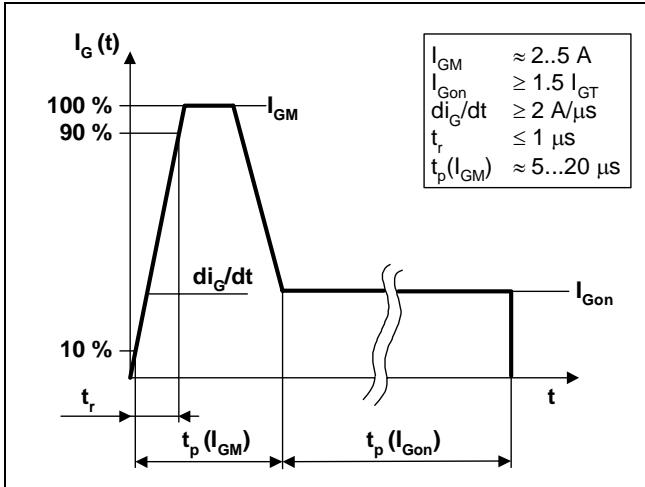


Fig. 6 Recommended gate current waveform

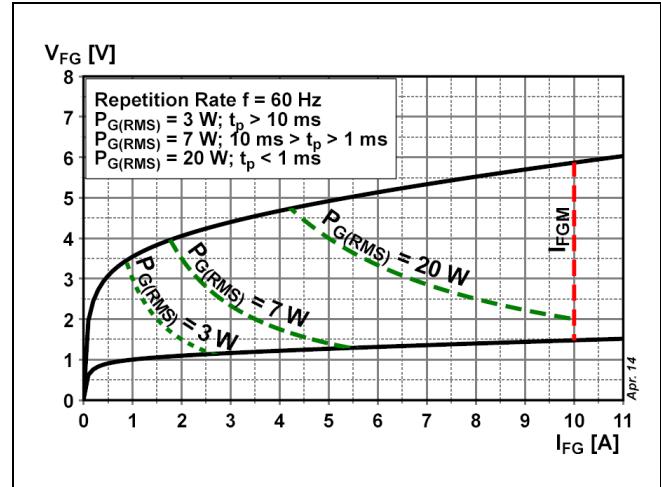


Fig. 7 Max. peak gate power loss

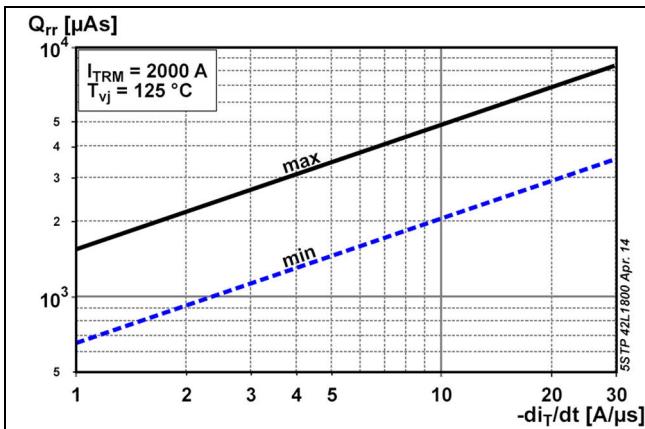


Fig. 8 Reverse recovery charge vs. decay rate of on-state current

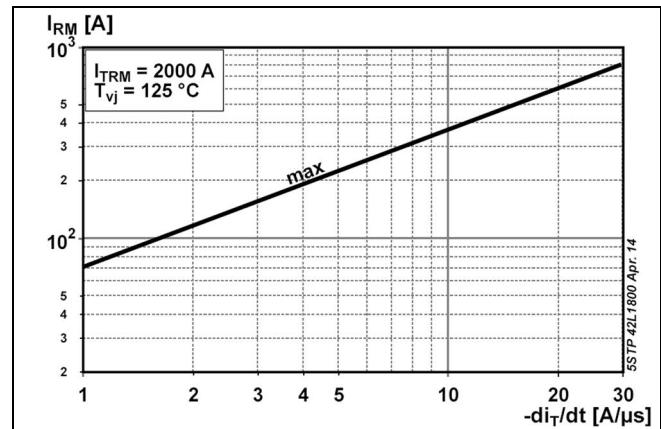
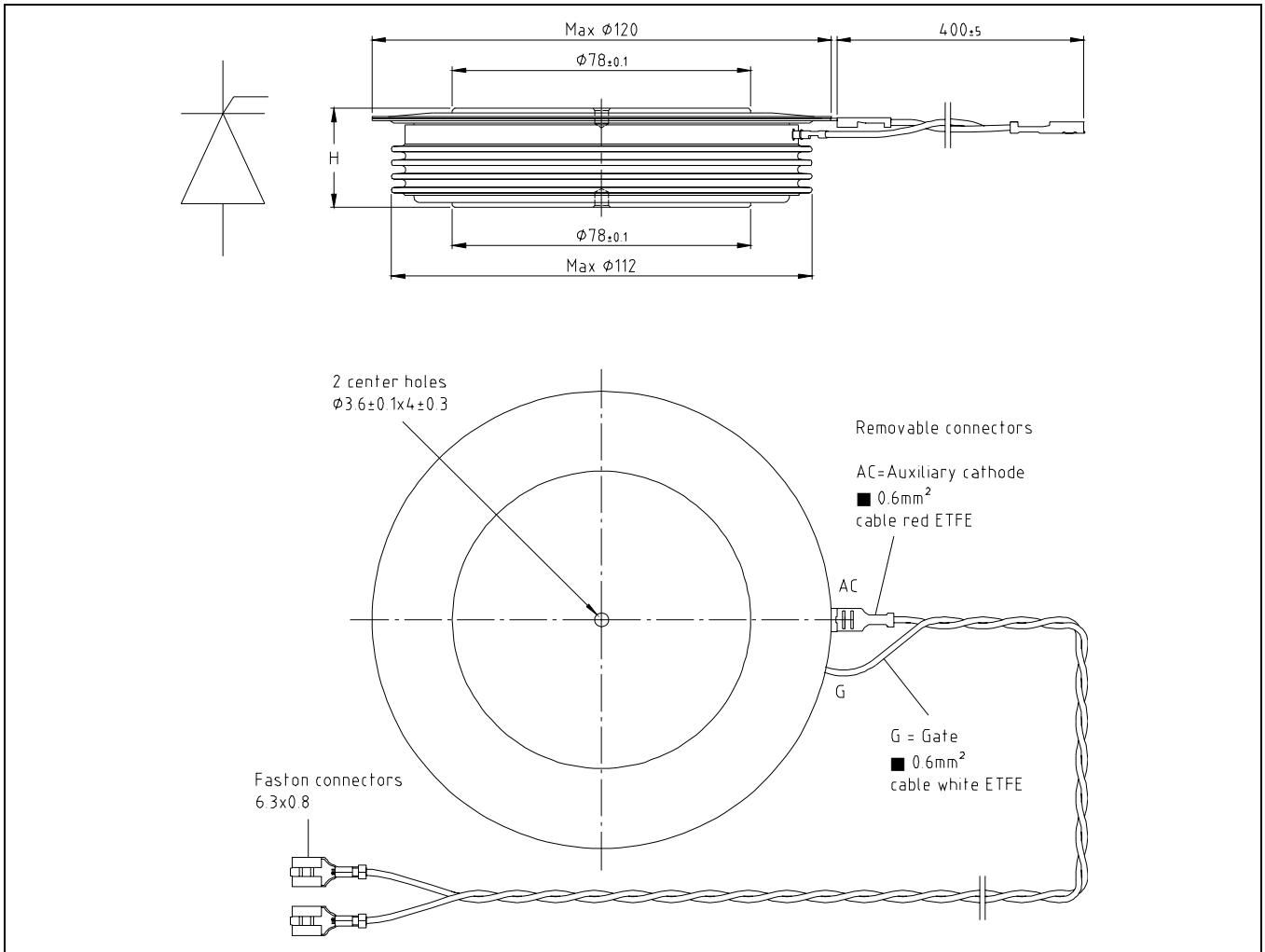


Fig. 9 Peak reverse recovery current vs. decay rate of on-state current



**Fig. 10** Device Outline Drawing

### Related documents:

- |           |  |
|-----------|--|
| 5SYA 2020 | Design of RC-Snubber for Phase Control Applications  |
| 5SYA 2049 | Voltage definitions for phase control thyristors and diodes                                    |
| 5SYA 2051 | Voltage ratings of high power semiconductors   |
| 5SYA 2034 | Gate-Drive Recommendations for PCT's   |
| 5SYA 2036 | Recommendations regarding mechanical clamping of Press Pack High Power Semiconductors          |
| 5SYA 2102 | Surge currents for Phase Control Thyristors  |
| 5SZK 9104 | Specification of environmental class for pressure contact diodes, PCTs and GTO, STORAGE        |
| 5SZK 9105 | Specification of environmental class for pressure contact diodes, PCTs and GTO, TRANSPORTATION |
| 5SZK 9115 | Specification of environmental class for presspack Diodes, PCTs and GTOs, OPERATION (Industry) |
| 5SZK 9116 | Specification of environmental class for presspack Diodes, PCTs and GTOs, OPERATION (Traction) |

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